Y H

Item And Code No.	
I T E M	CONNECTOR
S P E C	2.50㎜ Pitch Wire to Board DIP type
M A K E R S P E C	
Code No.	

The Best Partner for Electronic Circuits Connections

www.yeonho.com

Specification Approval Sheet

YEONHO ELECTRONICS CO.,LTD

Head Office & Laboratory : 14F, 234, Teheranro, Gangnam-gu, Seoul, Korea
TEL: 02)3453-0871 FAX: 02)3453-1468

Korea Factory : 43-28, Pyeongdong-ro 803 beon-gil, Gwangsan-gu, Gwangju, Korea
TEL: 062)952-0772 FAX: 062)952-0782

Indonesia Factory : JL. Industri Selatan 3A SFB block GG-3 C,D,E Jababeka II Cikarang-Bekasi 17550, Indonesia
TEL: 62-21)898-33225 FAX: 62-21)898-33228

Philippines Factory : Blk4, Lot6~9. Phase1, FCIE, Brgy. Langkaan, Dasmarinas, Cavite 4114, Philippines
TEL: 63-46)402-1921, 1924 FAX: 63-46)402-1928

Pitch	2.50 mm
Special	Wire to Board
Type	DIP

SM250 Series
Connector 제품규격
Product Specification

Indemnification

Yeonho will indemnify, hold harmless, and at buyer's request, defend buyer and buyer's directors, officers, employees, agents and independent contractors from and against any loss, cost, liability or expense (including court costs and reasonable fees of attorneys and other professionals) arising out of or resulting from any third party claim that any products and/or components provided by yeonho infringes patent, copyright, trade secret right or other intellectual property right.
if yeonho receives notice of an alleged patent, copyright, trade secret or other intellectual property right infringement or if buyer's use of the products and/or the components provided by yeonho shall be prevented by permanent injunction for reasons of patent, copyright or trade secret infringement, yeonho may, at its sole option and expense, procure for buyer the right to continued use of the products and/or the components as provided hereunder, or modify the allegedly infringing item such that it is no longer infringing, or replace the allegedly infringing item.

● 제,개정 이력『History Revision』

NO	DATE	ISS.	CHK.	APP.	SUMMARY
1	2001.10.15	P.K.H	A.J.I	B.J.S	Presentation
2	2002.10.04	C.A.N	J.J.E	A.J.I	염수분무 시험조건 개정
3	2003.01.21	C.A.N	J.J.E	A.J.I	특허문구 삽입
4	2004.06.07	K.H.S		A.J.I	시험방법 및 시험조건 개정

아래와 같이 사양 승인원을 제출합니다.

『Yeon Ho Electronics CO.,LTD. submits the approval certification of connector specification.』

1. 업 체 명 : (주) 연 호 전 자
   『Manufactured by : Yeon Ho Electronics CO.,LTD.』
2. 기 안 부 서 : 품질관리실
   『Written by : Quality Control Department』

♠♠♠ 목 차 『Contents』 ♠♠♠

1. 적용범위 『Scope』
2. 형명구성 『Numbering System of Products (Ordering Information of Products)』
3. 원 재 료 『Material Specifications』
4. 정 격 『Ratings』
5. 성 능 『Performance』
6. 포장 및 식별표시 『Identification & Packing』
7. 사용상 주의사항 『Caution for Use』

♠♠♠ 별 첨 『Attachment』 ♠♠♠

1. 검사성적서 『Reliability Test Report』
2. 사 양 도 『Drawings』
3. 재질증명서 『Material Certification』
4. 유해물질 분석 Data 『The Analysis Data of Hazardous Substance』
5. 물질안전보건자료 『MSDS Data』
6. Q.C 공정도 『QC Process Chart』

1. 적용 범위 『Scope』

본 사양서는 (주)연호전자 제품 SM250 series DIP type connector에 한하여 적용한다.
『This specification covers the requirements for SM250 series DIP type connector』

2. 형명 구성 『Numbering System of Products(Ordering Information of Products)』

SM W 250 - NN
- NN : Number of Circuits
- W : Parts : Straight Wafer
- 250 : Series Name

SM H 250 - NN L
- NN : Number of Circuits
- H : Parts : Housing
- 250 : Series Name

SM H 250J - NN RT(RE) — Parts : Retainer

YST 025L — Parts : Terminal

3. 원재료 『Material』

Item	Material	Maker	Plated / Color
Wafer Material	PA66	Rhodia	Natural
Housing Material	PA66	LG Chem	White
Rt Material	PA66	Rhodia	Red
Pin Material	Brass	Poongsan	Tin plated
Terminal Material	Phosphor Bronze	Poongsan	Tin plated

4. 정 격 『Ratings』

항 목 (Item)	정 격 (Standard Data)
정격 전압 (Operating Voltage)	AC/DC 250V
정격 전류 (Current Rating)	AC/DC 3A
사용 온도 (Operating Temperature)	-25℃ ~ +85℃
적용 전선 (Applicable Wire)	AWG #22 ~ #28
적용 PCB (Applicable P.C.B))	1.2 ~ 1.6㎜

5. 성 능 『Performance Characteristics』

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
1.	외 관 치 수 『Dimensions 』		첨부 제품도에 준한다. 『Refer to drawings』
2.	전 기 적 성 능 『Electrical Characteristics』		
	2-1.절연저항	⦿ 인접 Terminal(Contact)간에 DC 500V ±5V 전압을 1분±5초간 인가하였을 때 절연저항을 측정한다. (1회 측정에서 규격 치 미달인 경우 3시간 이내 재측정)	1000㏁ 이상
	2-1.Insulation Resistance	⦿ Measured between adjacent contacts ⦿ Test voltage : DC 500V ±5V / 1 min ±5 sec (Based upon MIL-STD-202G Method 302 Condition B)	1000㏁ MIN
	2-2.내 전 압	⦿ 인접한 Terminal간에 AC 1000V 전압을 1분±5초간 인가한다.	절연파괴/섬락이 없고 사용상 결함이 없을 것
	2-2.Dielectric Withstanding Voltage	⦿ Measured between adjacent contacts ⦿ Test voltage : AC 1000V / 1 min ±5 sec (Based upon MIL-STD-202G Method 301)	No flash over and no physical damage shall be observed
	2-3.접촉저항	⦿ Terminal과 Wafer Pin간의 접촉저항 측정 20mV. 10mA	30mΩ 이하
	2-3.Contact Resistance	⦿ Measured the resistance of mated connector, 20mV. 10mA	30mΩ MAX
3.	물 리 적 성 질 『Physical Characteristics』		
	3-1.납 땜 성	⦿ FLUX (ROSIN 10%, METHANOL 90%)에 5~10초 동안 담근 후 SnAg(3.5)Cu(0.7)의 Pot 납땜조 온도 (240℃±5℃)에 3초±0.5초 동안 침전시킨다.	침전 부위의 납땜이 90% 이상일 것
	3-1. Solder Ability	⦿ Immersion in flux consisting of rosin 10% and methanol 90% for a period of 5 to 10 seconds dip in molten solder consisting of SnAg(3.5)Cu(0.7) at 240℃± 5 ℃degrees for 3 ± 0.5 seconds	More than 90% of area dipped in molten solder should be coated by solder
	3-2.납땜내열성	※ WAVE TYPE ⦿ 온도 260℃±5℃ 5±0.5초간 침적시킨다.	외관 변형등이 없을 것
	3-2.Solder Heat Resistance	※ WAVE TYPE ⦿ Solder consisting : 260℃±5℃ degrees for 5±0.5 seconds	Appearance : Good
	3-3.Pin유지력	⦿ 사출물(수지)이 Pin을 유지하고 있는 힘 측정 * Pin을 25±3mm/min 속도로 뺄 때의 힘을 측정한다.	0.5Kgf 이상
	3-3.Pin Retention Force	⦿ Measured withdrawal force that resin grips and supports pin * Velocity of withdrawal : 25 ±3mm/min	0.5Kgf MIN

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	3-4.총합삽입력 3-4.Total Insertion Force	⊙ 회로수가 같은 Housing Ass`Y에 Wafer Ass`Y를 삽입할 때의 힘 측정 ⊙ Measured force to insert wafer assembly into the housing assembly which has same circuits	Pos / Push(Kgf) / Pull(Kgf) 2 / 1.5 Max / 0.30 Min 3 / 1.7 〃 / 0.35 〃 4 / 2.0 〃 / 0.40 〃 5 / 2.3 〃 / 0.50 〃 6 / 2.6 〃 / 0.60 〃 7 / 3.0 〃 / 0.70 〃 8 / 3.4 〃 / 0.80 〃 9 / 3.8 〃 / 1.00 〃 10 / 4.2 〃 / 1.20 〃 11 / 4.6 〃 / 1.40 〃 12 / 5.0 〃 / 1.60 〃 13 / 5.4 〃 / 1.80 〃 14 / 5.8 〃 / 2.00 〃 15 / 6.4 〃 / 2.20 〃 V TYPE 16 / 8.0 Max / 2.2 Min 24 / 10.0 〃 / 3.0 〃 28 / 11.0 〃 / 3.4 〃
	3-5.총합발거력 3-5.Total Withdrawal Force	⊙ 결합된 Housing Ass`Y로부터 Wafer Ass`Y를 발거할 때의 힘 측정 ⊙ Measured force to withdrawal wafer assembly from the housing assembly which has same circuits	
	3-6.내구성시험 3-6.Durability of Contact Resistance	⊙ 결합된 제품 Housing Ass`Y과 Wafer Ass`Y의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 접촉저항 측정 ⊙ Measured contact resistance after 30 cycles of total insertion and withdrawal operation ⊙ Withdrawal rate : 10th/min.	접촉저항 : 50mΩ 이하 Contact Resistance : 50mΩ MAX
	3-7.Terminal 삽입력 3-7.Insertion Force of Terminal	⊙ Housing을 고정시키고 Terminal를 25 ±3㎜/min 속도로 일직선으로 삽입할 때의 삽입력 측정 ⊙ Insert a terminal into the housing straightly and measure insertion force ⊙ Velocity of insertion : 25 ±3mm/min	1.0Kgf 이하 1.0Kgf MAX
	3-8.Terminal 조립강도 3-8.Terminal Retention Force	⊙ Housing에 Terminal을 조립한 후 Terminal을 25 ±3mm/min 속도로 인장시켜 이탈될 때의 힘 측정 ⊙ Insert a terminal into the housing and measure the force to withdraw the terminal from housing ⊙ Apply axial pull out force at the speed rate of 25 ±3mm/minute	0.5Kgf 이상 0.5Kgf MIN
	3-9.압착강도 3-9.Crimp Tensile Strength	⊙ Terminal에 Lead Wire를 압착한후 압착부위(심선부위)가 파괴될 때까지 25 ±3㎜/min 속도로 인장강도 측정 ⊙ Measured tensile strength of the crimped contact (stripped wire barrel section of contact) to conductor joint	AWG #22 : 2.5Kgf MIN AWG #24 : 2.0Kgf MIN AWG #26 : 1.5Kgf MIN AWG #28 : 1.0Kgf MIN

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
4.	환 경 시 험 『Environmental Test』		
	4-1.내진동성 시 험	⊙ DC 100mA 통전상태에서 진폭1.52mm 진동수 10-55-10HZ 진동 상태에서 X,Y,Z방향으로 각각 2시간씩 진동을 시킨 후 단전상태 및 접촉저항 측정	1)접촉저항: 50mΩ 이하 2)단전상태: 1μsec 동안 단전상태 없을 것
	4-1.Vibration	⊙ Current of 100mA shall be applied during the testing The vibration shall be along each axis for the period of two hours with the maximum amplitude of 1.52mm and frequency of 10-55-10Hz/Min (Based upon MIL-STD-202G Method 201A)	1)Contact Resistance : 50mΩ MAX 2)Discontinue : 1μsec MAX
	4-2.염수분무 시 험	⊙ Connector를 결합한 상태에서 아래 조건으로 시험 후 흐르는 물에 세척 후 상온에서 4시간 방치 후에 특성을 측정한다. 조건: 염수농도 5% ±1% 염수분무 시간 48시간 ±4시간 시험온도 35℃ ±2℃	1)접촉저항: 50mΩ 이하 2)외관: 흑녹현상 없을것
	4-2.Salt Spray	⊙ Measure after exposure to salt solution spray of 5 ±1% density at a temperature of 35℃ ±2℃ for 48hrs ±4hrs after test wash and leave to dry (Based upon MIL-STD-202G Method 101E Condition B)	1)Contact Resistance : 50mΩ MAX 2)Appearance : Not black rust
	4-3.내습성시험	⊙ Connector를 결합한 상태에서 아래조건에 따라 시험을 행한 후 측정한다. 조건 : 시험조의 온도 40℃ ±2℃ 상 대 습 도 90% ~ 95% 시 험 시 간 96시간	1)절연저항: 500MΩ 이상 2)접촉저항: 50mΩ 이하 3)외관 : 양호할 것
	4-3.Humidity	⊙ Mated connector shall be left for 96 hrs in an environment of 40 ±2℃, and 90 ~ 95% humidity. After the exposure the connector shall be left in an ambient condition for one hour before the measurement is done (Based upon MIL-STD-202G Method 103B Condition B)	1)Insulation Resistance : 500MΩ MIN 2)Contact Resistance : 50mΩ MAX 3)Appearance : Good
	4-4.내고온성 시 험	⊙ Connector를 결합한 상태에서 시험조의 온도 85 ±2℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 50mΩ 이하
	4-4.Resistance to High Temperature	⊙ Chamber temperature : 85 ±2℃ Exposed 30 minutes after being exposed 96 hrs under the chamber temperature electrical characteristics were measured and tested (Based upon MIL-STD-202G Method 108A Condition A)	1)Contact Resistance : 50mΩ MAX
	4-5.내한성시험	⊙ Connector를 결합한 상태에서 시험조의 온도 -40 ±3℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 50mΩ 이하
	4-5.Altitude Low Temperature	⊙ Chamber temperature : -40 ±3℃ Exposed 30 minutes after being exposed 96 hrs under the chamber temperature electrical characteristics were measured and tested (Based upon JIS C60068-2-1)	1)Contact Resistance : 50mΩ MAX

<table>
<tr><th>NO.</th><th>시험항목
『Test Title』</th><th>시 험 방 법 및 조 건
『Test Procedures/Methods Conditions』</th><th>규 격
『Requirements』</th></tr>
<tr><td></td><td>4-6.열충격시험</td><td>⊙ Connector를 결합한 상태에서 아래조건에 따라 5회 연속 시험을 행한 후 시험을 실시한다.
<table>
<tr><td>단 계</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>온도(℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>시간(분)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것
2)접촉저항: 50mΩ 이하
3)절연저항: 500MΩ 이상
4)외관 : 양호할 것</td></tr>
<tr><td></td><td>4-6.Thermal Shock</td><td>⊙ Mated connector shall be exposed five cycles as table #1 (Based upon MIL-STD-202G Method 107-A table #1)
<table>
<tr><td>STEP</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>Temperature (℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>Exposed Time (MIN)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)Dielectric Strength
: No flash over and no physical damage shall be observed
2)Contact Resistance
: 50mΩ MAX
3)Insulation Resistance
: 500MΩ MIN
4)Appearance : Good</td></tr>
</table>

6. 포장 및 식별방법 『Identification and Packing』

1) 포장 조건 『Packing Condition』 : Bulk Packing

2) 수 량 『Quantity』

3) 포장 방법 『Packing Method』

충분한 강도의 종이 BOX를 사용하여 충격을 방지하여 물리적 변형 또는 화학적 변화가 발생되지 않도록 하여야 한다

『 Carton box for shipment must have enough strength in order to protect physical damage during transportation.』

4) 식별 표시 ; 다음과 같은 사항을 제품포장 BOX에 명기한다.

『Identifications shall be marked as follows』

4-1. 제조회사, 제조자명 또는 상표 『Manufacture's LOGO』

4-2. 형명 또는 부품번호 『Part Number』

4-3. 수 량 『Quantity』

4-4. 제조 LOT NO 『Date Code』

4-5. 기타 상호 필요하다고 인정되는 사항

『Others agreed with manufacturer and customer』

7. 사용상 주의사항 『Caution for Use』

본 connector는 강(强)Lock 사양이므로, Connector 감합후의 Wire Harness의 부정확한 취급방향이나 과도하게 잡아당길 경우에는 납땜부의 파괴, Lock등 Connector자체의 파괴 또는 실장기판의 파괴등 Trouble를 발생시킬 가능성이 있습니다.
이와 같은 Trouble을 미연에 방지하고, Connector 성능을 충분히 내기 위해서는, Wire Harness를 취급할 때 다음과 같은 주의를 바랍니다.

『This connector is secure lock type, so the connector must be treated with care after mated. Incorrect handling direction and excessive pulling load to the wire harness may cause troubles which affect its performances such as degradation at solder tail, breakage of connector itself (lock devise, etc.) and a PCB for mounting. To prevent these troubles and make full use of connector's performances, special care should be taken on the following points when handling the wire harness.』

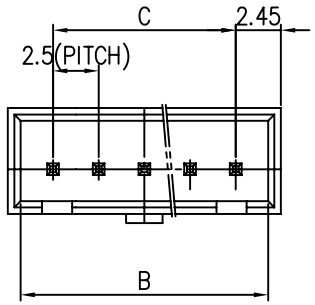
1) Connector에는 평소 Wire Harness 취급할 때, 인장하중 이외에 외력을 지속적으로 가하지 않는다.
『Do not apply an external force to a connector continuously except for pulling load and so on when handling wire harness as usual.』

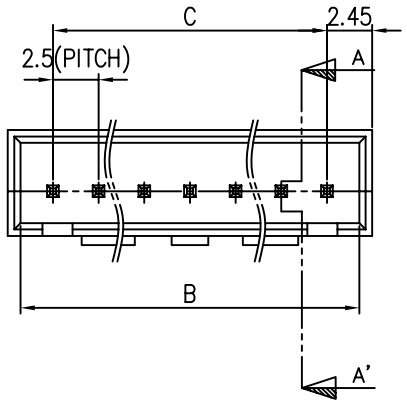
2) 전선에는 Connector의 삽발작업이 무리없이 이루어 질 수 있도록 “느슨하게” 설계하고 삽발작업은 감합축 선으로 한다.
『For the wire, make an appropriate looseness to mate and unmate the connector on the mating axis without strain.』

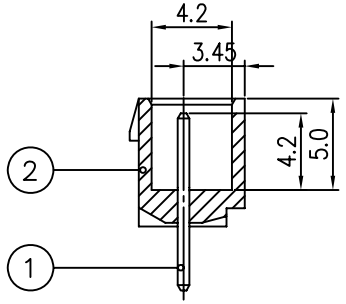
3) Connector에서 Wire Harness를 분리할 때에는 Lock을 완전히 해제하고 발거한다.
『When withdraw wire harness from the connector, Lock should be unlocked perfectly and withdraw.』

출도일	/ /	연구소

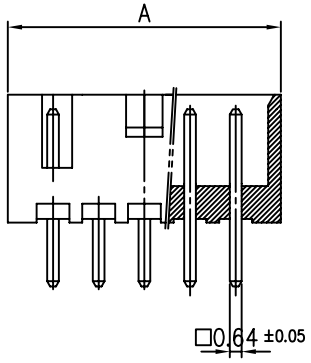
PART NO	PIN 수	A	B	C	COLOR
SMW250-02	02	7.4	5.8	2.50	K.B.Y.R
SMW250-03	03	9.9	8.3	5.00	K.B.Y.R
SMW250-04	04	12.4	10.8	7.50	K.B.Y.R
SMW250-05	05	14.9	13.3	10.00	K.B.Y.R
SMW250-06	06	17.4	15.8	12.50	K.B.Y.R
SMW250-07	07	19.9	18.3	15.00	K.B.Y.R
SMW250-08	08	22.4	20.8	17.50	K.B.Y.R
SMW250-09	09	24.9	23.3	20.00	K.B.Y.R
SMW250-10	10	27.4	25.8	22.50	K.B.Y.R
SMW250-11	11	29.9	28.3	25.00	K.B.Y.R
SMW250-12	12	32.4	30.8	27.50	K.B.Y.R
SMW250-13	13	34.9	33.3	30.00	K.B.Y.R
SMW250-14	14	37.4	35.8	32.50	K.B.Y.R
SMW250-15	15	39.9	38.3	35.00	K.B.Y.R



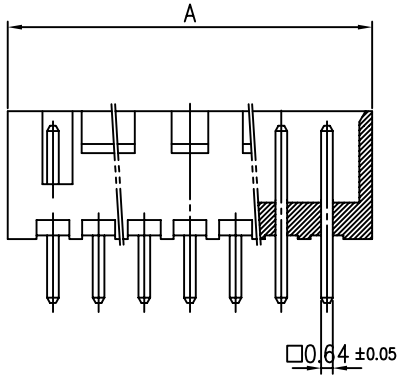




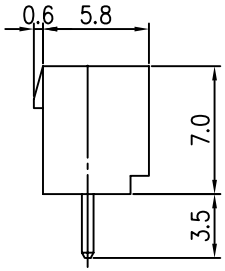
SECTION A-A'

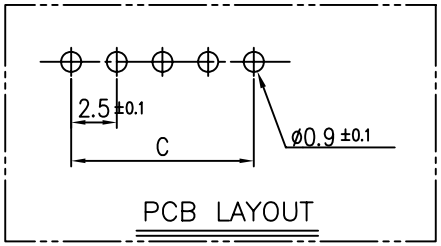


2-5pin 형상
(Locking 1개소)



6-15pin 형상
(Locking 3개소)





PCB LAYOUT

NOTE

1.G/TOL : ±0.3

2. PART No.:: SMW250-NN(*)

COLOR
표시없음---WHITE
BK --- BLACK
BL --- BLUE
YE --- YELLOW
RE --- RED
GR --- GREEN
VI --- VIOLET

NO	DESCRIPTION	MATERILAL	REMARK
2	PIN	BRASS	Tin-Plated
1	WAFER	NYLON66,UL94 V-0	

YEONHO ELECTRONICS CO., LTD.

TITLE: SMW250-NN

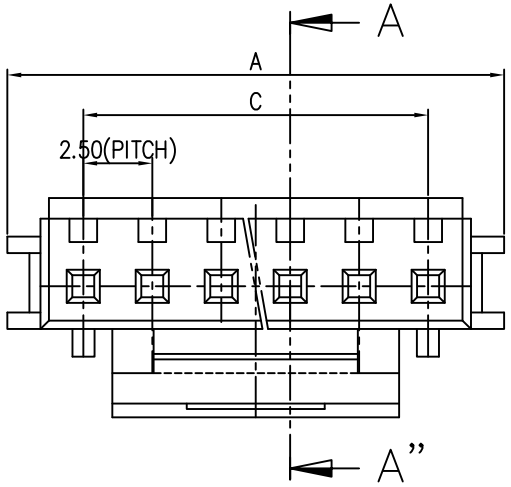
SCALE	DRAWN	DESIGN	CHECK	APPD
N/S	95.6.28	J J H	95.9.1	K S N

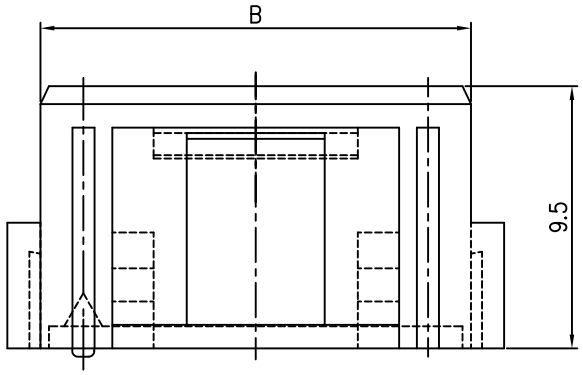
SIZE	DWG. NO	REV
A3	SMW250-00A-S	

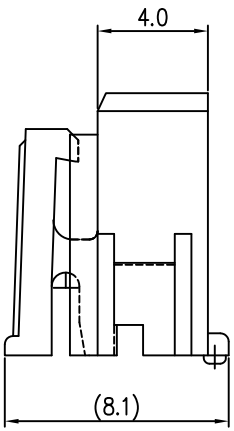
LTR	REVISION RECORD	DATE	DR	CHK

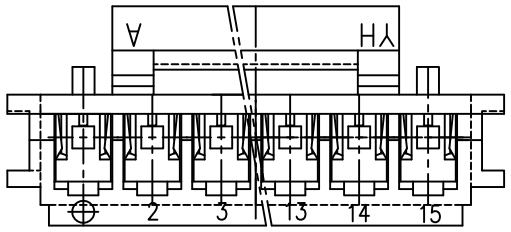
"본 도면은 연호전자의 지적자산이므로 임의 COPY 및 배포를 금합니다"

출도일	2004 / 07 / 21	연구소









PART NO.	A	B	C
SMH250-02L	8.0	5.6	2.50
SMH250-03L	10.5	8.1	5.0
SMH250-04L	13.0	10.6	7.50
SMH250-05L	15.5	13.1	10.0
SMH250-06L	18.0	15.6	12.5
SMH250-07L	20.5	18.1	15.0
SMH250-08L	23.0	20.6	17.5
SMH250-09L	25.5	23.1	20.0
SMH250-10L	28.0	25.6	22.5
SMH250-11L	30.5	28.1	25.0
SMH250-12L	33.0	30.6	27.5
SMH250-13L	35.5	33.1	30.0
SMH250-14L	38.0	35.6	32.5
SMH250-15L	40.5	38.1	35.0

NOTE

1. 관련TERMINAL : YST025-L
   WAFER : SMW250,SMAW250
   PLUG : 25045HP
2. 일반공차 : ±0.3
3. 형명구성 : SMH250-NNL (*)

COLOR
- 표기없음 --- NATURAL
- (WH) ---- WHITE
- (BK) ---- BLACK
- (BL) ---- BLUE
- (RE) ---- RED
- (YE) ---- YELLOW
- (BR) ---- BROWN
- (GR) ---- GRAY

1	HOUSING	NYLON 66 UL94V-0	NN	
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

YEONHO ELECTRONICS CO., LTD.

TITLE: SMH250-NNL

SCALE	DRAWN	DESIGN	CHECK	APPD
10/1 (20/1)	J. J	J	J. J	J
	04.07.21		04.07.21	

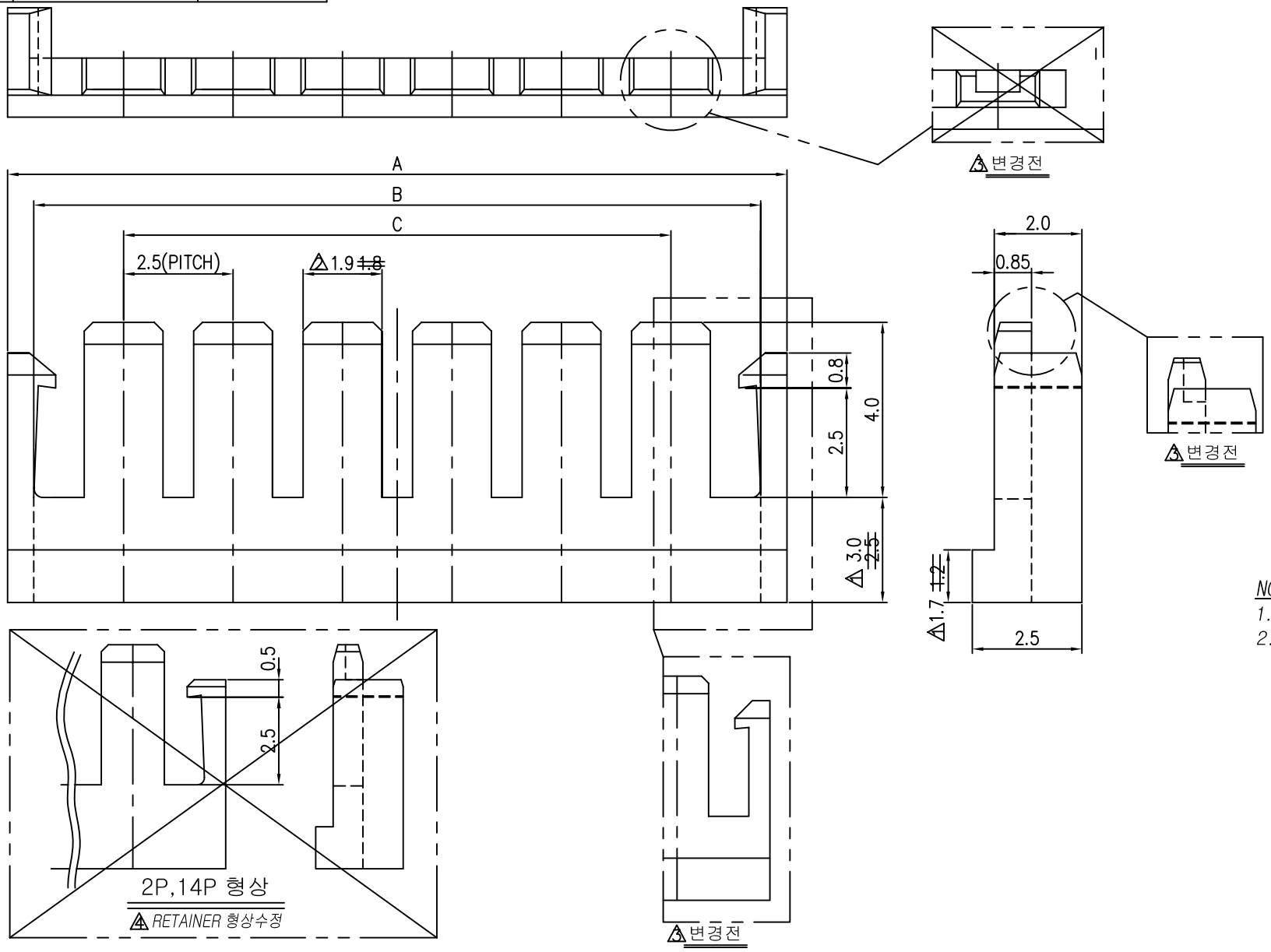
SIZE	DWG. NO	REV
A3	SMH250-00LS00	

LTR	REVISION RECORD	DR	CHK	ECN

"본 도면은 연호전자의 지적자산이므로 임의 COPY 및 배포를 금합니다"

출 도 일	/ /	연 구 소

PART NO.	A	B	C
SMH250J-02RT	7.8	6.6	2.5
SMH250J-03RT	10.3	9.1	5.0
SMH250J-04RT	12.8	11.6	7.5
SMH250J-05RT	15.3	14.1	10.0
SMH250J-06RT	17.8	16.6	12.5
SMH250J-07RT	20.3	19.1	15.0
SMH250J-08RT	22.8	21.6	17.5
SMH250J-09RT	25.3	24.1	20.0
SMH250J-10RT	27.8	26.6	22.5
SMH250J-11RT	30.3	29.1	25.0
SMH250J-12RT	32.8	31.6	27.5
SMH250J-13RT	35.3	34.1	30.0
SMH250J-14RT	37.8	36.6	32.5
SMH250J-15RT	40.3	39.1	35.0



NOTE
1. 일반공차 : ±0.3
2. 형명구성 : SMH250J-NNRT

LTR	REVISION RECORD	DR	CHK	ECN
△4	RETAINER 02P, 14P 형상수정(작업성 개선)	10.03.08	K.K.S	C.J.W
△3	RETAINER 기능 강화(형상삭제)	05.03.03	H.S.K	C.J.W
△2	터미널 밀림방지 살보강 (1.8-->1.9MM)	04.08.31	K.K.S	
△1	표시부 시방변경(살보강 2.5--3.0MM)	04.07.06	J.J.H	

"본 도면은 연호전자의 지적자산이므로 임의 COPY 및 배포를 금합니다"

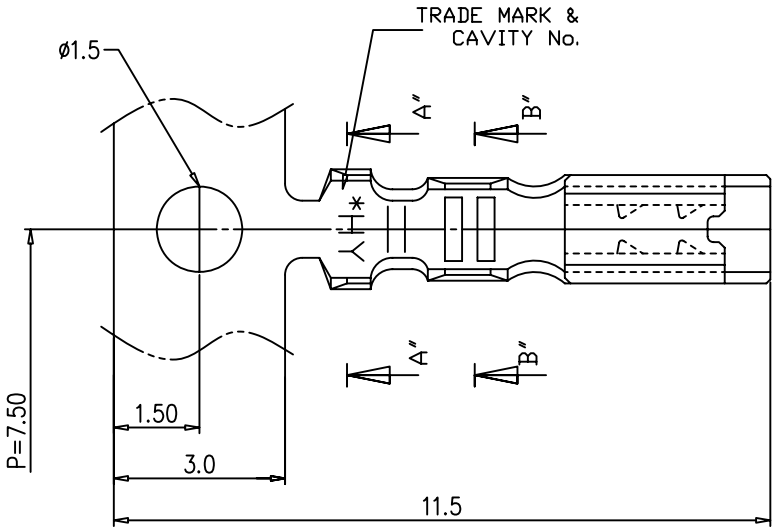
I/NO	DESCRIPTION	MATERIAL	TREATMENT	QTY	REMARK
	RETAINER	NYLON 66	UL94V-0	NN	

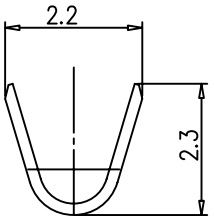
YEONHO ELECTRONICS CO., LTD.

SCALE	DRAWN	DESIGN	CHECK	APPD
10/1	C. B. H 01.12.04		K. S. N 02.06.25	

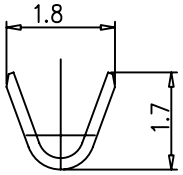
TITLE: SMH250J-NNRT (RETAINER)

SIZE	DWG. NO	REV
A3	25037RT-00A-S	04

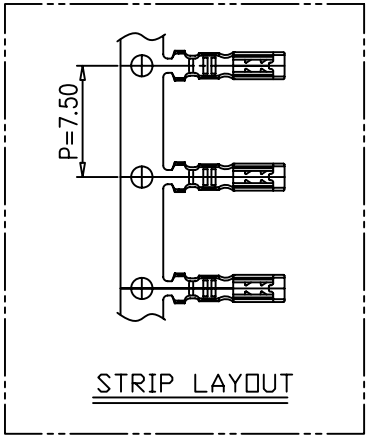




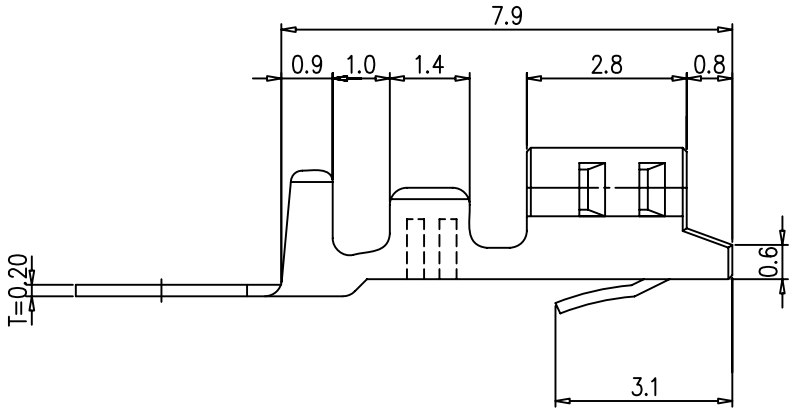
SEC A-"A"

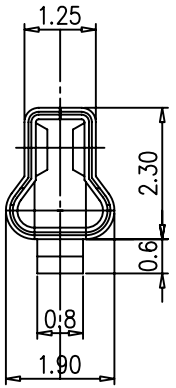


SEC B-"B"



STRIP LAYOUT





NOTE
1. GENERAL TOLERLANCE ±0.3
2. FINISH : TIN PLATED.
3. 사용전선 : AWG #22 - # 28.
4. 피복외경 : ø1.2 - ø2.4.
5. 관련부품
   - HOUSING : SMH250-NNL.

	TERMINAL	P, Bronze	TIN - PLATED		
I/NO	DESCRIPTION	MATERIAL	TREATMENT	QTY	REMARK

YEONHO ELECTRONICS CO., LTD.

TITLE: YST025-L

SCALE	DRAWN	DESIGN	CHECK	APPD
10/1 (20/1)	C.B.H 02.11.26		K.S.N 02.11.26	

SIZE	DWG. NO	REV
A3	YST025-L0S00	

LTR	REVISION RECORD	DATE	DR	CHK